

MC1458, MC1558 DUAL GENERAL-PURPOSE OPERATIONAL AMPLIFIERS

SLOS069C – FEBRUARY 1971 – REVISED AUGUST 2010

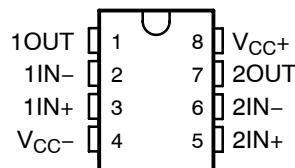
- Short-Circuit Protection
- Wide Common-Mode and Differential Voltage Ranges
- No Frequency Compensation Required
- Low Power Consumption
- No Latch-Up
- Designed to Be Interchangeable With Motorola MC1558/MC1458 and Signetics S5558/N5558

description/ordering information

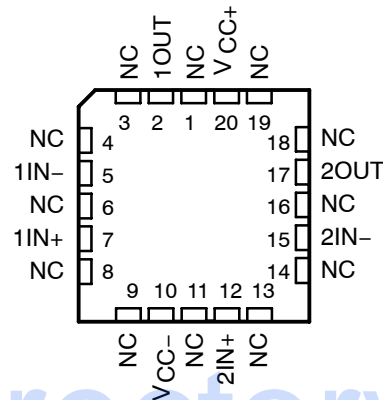
The MC1458 and MC1558 are dual general-purpose operational amplifiers, with each half electrically similar to the μ A741, except that offset null capability is not provided.

The high-common-mode input voltage range and the absence of latch-up make these amplifiers ideal for voltage-follower applications. The devices are short-circuit protected and the internal frequency compensation ensures stability without external components.

MC1458 . . . D, P, OR PS PACKAGE
MC1558 . . . JG PACKAGE
(TOP VIEW)



MC1558 . . . FK PACKAGE
(TOP VIEW)



NC – No internal connection

ORDERING INFORMATION

| T_A | V_{IOmax} AT 25°C | PACKAGE† | | ORDERABLE PART NUMBER | TOP-SIDE MARKING |
|----------------|------------------------|------------|---------------|--------------------------|---------------------|
| 0°C to 70°C | 6 mV | PDIP (P) | Tube | MC1458P | MC1458P |
| | | SOIC (D) | Tube | MC1458D | MC1458 |
| | | | Tape and reel | MC1458DR | |
| | | SOP (PS) | Tape and reel | MC1458PSR | M1458 |
| -55°C to 125°C | 5 mV | CDIP (JG) | Tube | MC1558JG | MC1558JG |
| | | CDIP (JGB) | Tube | MC1558JGB | MC1558JGB |
| | | LCCC (FK) | Tube | MC1558FK | MC1558FK |

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



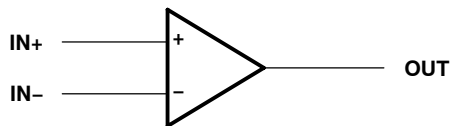
POST OFFICE BOX 655303 • DALLAS, TEXAS 75265
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On products compliant to MIL-PRF-38535, all parameters are tested unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters.

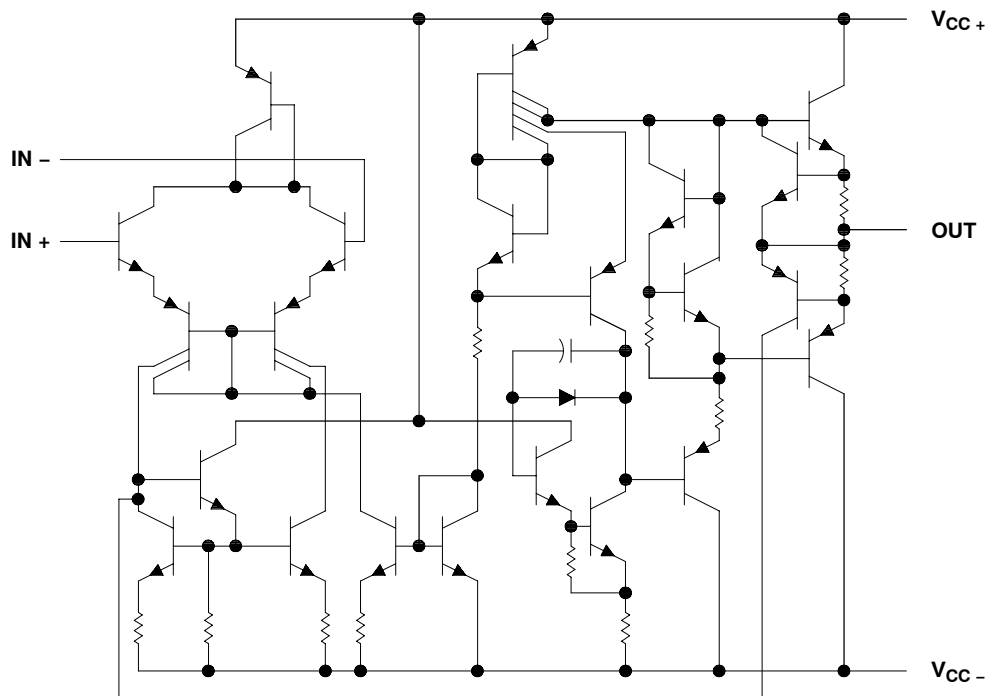
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SLOS069C - FEBRUARY 1971 - REVISED AUGUST 2010

symbol (each amplifier)



schematic (each amplifier)



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SLOS069C – FEBRUARY 1971 – REVISED AUGUST 2010

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

| | | |
|---|------------------|----------------|
| Supply voltage, V_{CC+} (see Note 1): | MC1458 | 18 V |
| | MC1558 | 22 V |
| Supply voltage, V_{CC-} (see Note 1): | MC1458 | -18 V |
| | MC1558 | -22 V |
| Differential input voltage, V_{ID} (see Note 2) | | ± 30 V |
| Input voltage, V_I (either input, see Notes 1 and 3) | | ± 15 V |
| Duration of output short circuit (see Note 4) | | Unlimited |
| Operating virtual junction temperature, T_J | | 150°C |
| Package thermal impedance, θ_{JA} (see Notes 5 and 6): | D package | 97°C/W |
| | P package | 85°C/W |
| | PS package | 95°C/W |
| Package thermal impedance, θ_{JC} (see Notes 7 and 8): | FK package | 5.61°C/W |
| | JG package | 14.5°C/W |
| Case temperature for 60 seconds: FK package | | 260°C |
| Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds: JG package | | 300°C |
| Lead temperature 1,6 mm (1/16 inch) from case for 60 seconds: D, P, or PS package | | 260°C |
| Storage temperature range, T_{stg} | | -65°C to 150°C |

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES:
1. All voltage values, unless otherwise noted, are with respect to the midpoint between V_{CC+} and V_{CC-} .
 2. Differential voltages are at $IN+$ with respect to $IN-$.
 3. The magnitude of the input voltage must never exceed the magnitude of the supply voltage or 15 V, whichever is less.
 4. The output can be shorted to ground or either power supply. For the MC1558 only, the unlimited duration of the short circuit applies at (or below) 125°C case temperature or 70°C free-air temperature.
 5. Maximum power dissipation is a function of $T_J(\max)$, θ_{JA} , and T_A . The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_J(\max) - T_A)/\theta_{JA}$. Operating at the absolute maximum T_J of 150°C can affect reliability.
 6. The package thermal impedance is calculated in accordance with JESD 51-7.
 7. Maximum power dissipation is a function of $T_J(\max)$, θ_{JC} , and T_C . The maximum allowable power dissipation at any allowable case temperature is $P_D = (T_J(\max) - T_C)/\theta_{JC}$. Operating at the absolute maximum T_J of 150°C can affect reliability.
 8. The package thermal impedance is calculated in accordance with MIL-STD-883.

recommended operating conditions

| | | MIN | MAX | UNIT |
|-------------|--------------------------------------|--------|---------|------|
| $V_{CC\pm}$ | Supply voltage | ±5 | ±15 | V |
| T_A | Operating free-air temperature range | MC1458 | 0 70 | °C |
| | | MC1558 | -55 125 | |



MC1458, MC1558 DUAL GENERAL-PURPOSE OPERATIONAL AMPLIFIERS

SLOS069C – FEBRUARY 1971 – REVISED AUGUST 2010

electrical characteristics at specified free-air temperature, $V_{CC\pm} = \pm 15\text{ V}$

| PARAMETER | TEST CONDITIONS† | MC1458 | | | MC1558 | | | UNIT |
|--|---|-------------|-----|-----|--------|------|------------------------|------|
| | | MIN | TYP | MAX | MIN | TYP | MAX | |
| V_{IO} Input offset voltage | $V_O = 0$ | 25°C | 1 | 6 | 1 | 5 | mV | |
| | | Full range | | 7.5 | | 6 | | |
| I_{IO} Input offset current | $V_O = 0$ | 25°C | 20 | 200 | 20 | 200 | nA | |
| | | Full range | | 300 | | 500 | | |
| I_{IB} Input bias current | $V_O = 0$ | 25°C | 80 | 500 | 80 | 500 | nA | |
| | | Full range | | 800 | | 1500 | | |
| V_{ICR} Common-mode input voltage range | | 25°C | ±12 | ±13 | ±12 | ±13 | V | |
| | | Full range | ±12 | | ±12 | | | |
| V_{OM} Maximum peak output voltage swing | $R_L = 10\text{ k}\Omega$ | 25°C | ±12 | ±14 | ±12 | ±14 | V | |
| | $R_L \geq 10\text{ k}\Omega$ | Full range | ±12 | | ±11 | | | |
| | $R_L = 2\text{ k}\Omega$ | 25°C | ±10 | ±13 | ±10 | ±13 | | |
| | $R_L \geq 2\text{ k}\Omega$ | Full range | ±10 | | ±10 | | | |
| A_{VD} Large-signal differential voltage amplification | $R_L \geq 2\text{ k}\Omega, V_O = \pm 10\text{ V}$ | 25°C | 20 | 200 | 50 | 200 | V/mV | |
| | | Full range | 15 | | 25 | | | |
| B_{OM} Maximum-output-swing bandwidth (closed loop) | $R_L = 2\text{ k}\Omega, A_{VD} = 1, THD \geq 5\%$ | 25°C | | 14 | | 14 | kHz | |
| B_1 Unity-gain bandwidth | | 25°C | | 1 | | 1 | MHz | |
| ϕ_m Phase margin | $A_{VD} = 1$ | 25°C | | 65 | | 65 | deg | |
| | | Gain margin | | 11 | | 11 | | |
| r_i Input resistance | | 25°C | 0.3 | 2 | 0.3* | 2 | M Ω | |
| r_o Output resistance | $V_O = 0, \text{ See Note 9}$ | 25°C | | 75 | | 75 | Ω | |
| C_i Input capacitance | | 25°C | | 1.4 | | 1.4 | pF | |
| z_{ic} Common-mode input impedance | $f = 20\text{ Hz}$ | 25°C | | 200 | | 200 | M Ω | |
| CMRR Common-mode rejection ratio | $V_{IC} = V_{ICR}\text{ min}, V_O = 0$ | 25°C | 70 | 90 | 70 | 90 | dB | |
| | | Full range | 70 | | 70 | | | |
| k_{SVS} Supply-voltage sensitivity ($\Delta V_{IO}/\Delta V_{CC}$) | $V_{CC} = \pm 9\text{ V to } \pm 15\text{ V}, V_O = 0$ | 25°C | 30 | 150 | 30 | 150 | $\mu\text{V/V}$ | |
| | | Full range | | 150 | | 150 | | |
| V_n Equivalent input noise voltage (closed loop) | $A_{VD} = 100, f = 1\text{ kHz}, R_S = 0, BW = 1\text{ Hz}$ | 25°C | | 45 | | 45 | nV/ $\sqrt{\text{Hz}}$ | |
| I_{OS} Short-circuit output current | | 25°C | ±25 | ±40 | ±25 | ±40 | mA | |
| I_{CC} Supply current (both amplifiers) | $V_O = 0, \text{ No load}$ | 25°C | 3.4 | 5.6 | 3.4 | 5 | mA | |
| | | Full range | | 6.6 | | 6.6 | | |
| P_D Total power dissipation (both amplifiers) | $V_O = 0, \text{ No load}$ | 25°C | 100 | 170 | 100 | 150 | mW | |
| | | Full range | | 200 | | 200 | | |
| V_{O1}/V_{O2} Crosstalk attenuation | | 25°C | | 120 | | 120 | dB | |

*On products compliant to MIL-PRF-38535, this parameter is not production tested.

† All characteristics are specified under open-loop operating conditions with zero common-mode input voltage, unless otherwise specified. Full range for MC1458 is 0°C to 70°C and for MC1558 is -55°C to 125°C.

NOTE 9: This typical value applies only at frequencies above a few hundred hertz because of the effect of drift and thermal feedback.



MC1458, MC1558 DUAL GENERAL-PURPOSE OPERATIONAL AMPLIFIERS

SLOS069C – FEBRUARY 1971 – REVISED AUGUST 2010

operating characteristics, $V_{CC\pm} = \pm 15\text{ V}$, $C_L = 100\text{ pF}$, $T_A = 25^\circ\text{C}$ (see Figure 1)

| PARAMETER | | TEST CONDITIONS | | MC1458 | | | MC1558 | | | UNIT |
|-----------|-------------------------|------------------------|----------------------------|--------|-----|-----|--------|-----|-----|------------------------|
| | | | | MIN | TYP | MAX | MIN | TYP | MAX | |
| t_r | Rise time | $V_I = 20\text{ mV}$, | $R_L = 2\text{ k}\Omega$, | 0.3 | | | 0.3 | | | μs |
| | Overshoot factor | $V_I = 20\text{ mV}$, | $R_L = 2\text{ k}\Omega$ | 5 | | | 5 | | | % |
| SR | Slew rate at unity gain | $V_I = 10\text{ V}$, | $R_L = 2\text{ k}\Omega$ | 0.5 | | | 0.5 | | | $\text{V}/\mu\text{s}$ |

PARAMETER MEASUREMENT INFORMATION



Figure 1. Rise-Time, Overshoot, and Slew-Rate Waveform and Test Circuit

PACKAGING INFORMATION

| Orderable Device | Status ⁽¹⁾ | Package Type | Package Drawing | Pins | Package Qty | Eco Plan ⁽²⁾ | Lead/ Ball Finish | MSL Peak Temp ⁽³⁾ | Samples (Requires Login) |
|------------------|-----------------------|--------------|-----------------|------|-------------|----------------------------|----------------------|------------------------------|-----------------------------|
| 5962-9760301Q2A | ACTIVE | LCCC | FK | 20 | 1 | TBD | Call TI | Call TI | |
| 5962-9760301QPA | ACTIVE | CDIP | JG | 8 | 1 | TBD | Call TI | Call TI | |
| MC1458D | ACTIVE | SOIC | D | 8 | 75 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | |
| MC1458DE4 | ACTIVE | SOIC | D | 8 | 75 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | |
| MC1458DG4 | ACTIVE | SOIC | D | 8 | 75 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | |
| MC1458DR | ACTIVE | SOIC | D | 8 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | |
| MC1458DRE4 | ACTIVE | SOIC | D | 8 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | |
| MC1458DRG4 | ACTIVE | SOIC | D | 8 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | |
| MC1458P | ACTIVE | PDIP | P | 8 | 50 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type | |
| MC1458PE4 | ACTIVE | PDIP | P | 8 | 50 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type | |
| MC1458PSR | ACTIVE | SO | PS | 8 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | |
| MC1458PSRE4 | ACTIVE | SO | PS | 8 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | |
| MC1458PSRG4 | ACTIVE | SO | PS | 8 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | |
| MC1558FKB | ACTIVE | LCCC | FK | 20 | 1 | TBD | POST-PLATE | N / A for Pkg Type | |
| MC1558JG | ACTIVE | CDIP | JG | 8 | 1 | TBD | A42 | N / A for Pkg Type | |
| MC1558JGB | ACTIVE | CDIP | JG | 8 | 1 | TBD | A42 | N / A for Pkg Type | |
| MC1558P | OBSOLETE | PDIP | P | 8 | | TBD | Call TI | Call TI | |
| SN98212P | OBSOLETE | PDIP | P | 8 | | TBD | Call TI | Call TI | |

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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OTHER QUALIFIED VERSIONS OF MC1558, MC1558M :

● Catalog: [MC1558](#)

● Military: [MC1558M](#)

NOTE: Qualified Version Definitions:

● Catalog - TI's standard catalog product

● Military - QML certified for Military and Defense Applications

TAPE AND REEL INFORMATION

REEL DIMENSIONS



TAPE DIMENSIONS



| | |
|----|---|
| A0 | Dimension designed to accommodate the component width |
| B0 | Dimension designed to accommodate the component length |
| K0 | Dimension designed to accommodate the component thickness |
| W | Overall width of the carrier tape |
| P1 | Pitch between successive cavity centers |

TAPE AND REEL INFORMATION

*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|-----------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| MC1458DR | SOIC | D | 8 | 2500 | 330.0 | 12.4 | 6.4 | 5.2 | 2.1 | 8.0 | 12.0 | Q1 |
| MC1458DR | SOIC | D | 8 | 2500 | 330.0 | 12.4 | 6.4 | 5.2 | 2.1 | 8.0 | 12.0 | Q1 |
| MC1458PSR | SO | PS | 8 | 2000 | 330.0 | 16.4 | 8.2 | 6.6 | 2.5 | 12.0 | 16.0 | Q1 |

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|-----------|--------------|-----------------|------|------|-------------|------------|-------------|
| MC1458DR | SOIC | D | 8 | 2500 | 367.0 | 367.0 | 35.0 |
| MC1458DR | SOIC | D | 8 | 2500 | 340.5 | 338.1 | 20.6 |
| MC1458PSR | SO | PS | 8 | 2000 | 367.0 | 367.0 | 38.0 |

JG (R-GDIP-T8)

CERAMIC DUAL-IN-LINE



- NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. This package can be hermetically sealed with a ceramic lid using glass frit.
 D. Index point is provided on cap for terminal identification.
 E. Falls within MIL STD 1835 GDIP1-T8

FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



| NO. OF TERMINALS ** | A | | B | |
|---------------------|------------------|------------------|------------------|------------------|
| | MIN | MAX | MIN | MAX |
| 20 | 0.342 (8,69) | 0.358 (9,09) | 0.307 (7,80) | 0.358 (9,09) |
| 28 | 0.442 (11,23) | 0.458 (11,63) | 0.406 (10,31) | 0.458 (11,63) |
| 44 | 0.640 (16,26) | 0.660 (16,76) | 0.495 (12,58) | 0.560 (14,22) |
| 52 | 0.740 (18,78) | 0.761 (19,32) | 0.495 (12,58) | 0.560 (14,22) |
| 68 | 0.938 (23,83) | 0.962 (24,43) | 0.850 (21,6) | 0.858 (21,8) |
| 84 | 1.141 (28,99) | 1.165 (29,59) | 1.047 (26,6) | 1.063 (27,0) |



4040140/D 01/11

- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package can be hermetically sealed with a metal lid.
 - Falls within JEDEC MS-004

P (R-PDIP-T8)

PLASTIC DUAL-IN-LINE PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Falls within JEDEC MS-001 variation BA.

D (R-PDSO-G8)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
 - D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
 - E. Reference JEDEC MS-012 variation AA.

D (R-PDSO-G8)

PLASTIC SMALL OUTLINE



4211283-2/E 08/12

- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate designs.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

MECHANICAL DATA

PS (R-PDSO-G8)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

PS (R-PDSO-G8)

PLASTIC SMALL OUTLINE



4212188/A 09/11

- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate designs.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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Products

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| Interface | interface.ti.com |
| Logic | logic.ti.com |
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| Wireless Connectivity | www.ti.com/wirelessconnectivity |

Applications

| | |
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| Medical | www.ti.com/medical |
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